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To: Examiner F. Toledo
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Fax No: 703-872-9306

Ph. No:

From: Andrew J. Telesz, Jr.


Subject: Serial No.: 10/689,936
Our Ref. No.: IIZ.003D2C

No. of Pages (including cover): 9

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Comments:

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CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)			Docket No.
Applicant(s): Takashi Ohsumi			U2.003D2C
Serial No. 10/689,936	Filing Date October 22, 2003	Examiner F. Toledo	Group Art Unit 2823
Invention: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS			
<p>I hereby certify that this <u>Letter Submitting Earlier Filed Information Disclosure Statement</u> (Identify type of correspondence)</p> <p>is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>703-872-9306</u>)</p> <p>on <u>July 1, 2005</u> (Date)</p> <p><u>Andrew J. Telesz, Jr.</u> (Typed or Printed Name of Person Signing Certificate)</p> <p> (Signature)</p> <p>Note: Each paper must have its own certificate of mailing.</p>			

Via Facsimile 703-872-9306**IIZ.003D2C****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re PATENT APPLICATION of

Takashi Ohsumi

Group Art Unit: 2823

**RECEIVED
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Serial No.: 10/689,936

Examiner: F. Toledo

JUL 01 2005

Filed: October 22, 2003

Conf. No.: 4027

**FOR: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS****LETTER RESUBMITTING EARLIER FILED INFORMATION DISCLOSURE
STATEMENT**

U.S. Patent and Trademark Office
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Randolph Building
401 Dulany Street
Alexandria, VA 22314

Date: July 1, 2005

Sir:

The Notice of Allowability received along with the Notice of Allowance dated June 15, 2005, does not acknowledge receipt of the Information Disclosure Statement filed on April 25, 2005, in connection with the above identified application.

Accordingly, enclosed is a copy of the Information Disclosure Statement and Form PTO/SB/08A form filed on April 25, 2005. Also enclosed is a copy of a dated, stamped postcard receipt provided as evidence that the above noted Information Disclosure Statement was received by the U.S. Patent Office on April 25, 2005.

**Applicant respectfully requests the Examiner to acknowledge that the
Information Disclosure Statement has been received, and to confirm that the**

Serial No.: 10/689,936

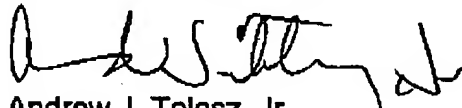
documents will be cited of record.

In the event that there are any outstanding matters remaining in the present application, please contact Andrew J. Telesz, Jr. (Reg. No. 33,581) at (571) 283-0720 in the Washington, D.C. area, to discuss these matters.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment for any additional fees that may be required, or credit any overpayment, to Deposit Account No. 50-0238.

Respectfully submitted,

VOLENTINE FRANCOS & WHITT, P.L.L.C.



Andrew J. Telesz, Jr.
Registration No. 33,581

11951 Freedom Drive, Suite 1260
Reston, Virginia 20190
Telephone No.: (571) 283-0720
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Enclosures: • Copy of Information Disclosure Statement and PTO/SB/08A form filed on
April 25, 2005
• Copy of dated, stamped postcard receipt

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))Docket No.
H2.003D2C

In Re Application Of: Takashi Ohsumi

Application No.

10/689,936

Filing Date

October 22, 2003

Examiner

R. Toledo

Customer No.

Group Art Unit

2823

Confirmation No.

4027

Title: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER
WITH REDUCED THERMAL STRESS

Address to:

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450**37 CFR 1.97(b)**

1. ☐ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

37 CFR 1.97(c)

2. ☒ The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

☒ the statement specified in 37 CFR 1.97(e);

OR

☐ the fee set forth in 37 CFR 1.17(p).

Note: The references listed on Form PTO/SB/08A were cited in copending U.S. Application Serial No. 10/957,620, and thus may be material to the prosecution of the present application.

P10A/REV05

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT

(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
H2.003D2C

In Re Application: Takashi Ohsumi

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/689,936	October 22, 2003	F. Toledo		2823	4027

Title: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- ☐ A check in the amount of _____ is attached.
- ☒ The Director is hereby authorized to charge and credit Deposit Account No. 50-0238 as described below.
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Typed or Printed Name of Person Mailing Certificate _____

*This certificate may only be used if paying by deposit account.

Dated: April 25, 2005

ANDREW J. TELESZ, JR.
EG. NO. 33,581

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ESTON, VA 20190
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P104REV05

**STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING
INFORMATION DISCLOSURE STATEMENT**Docket No.
H2.003D2C

In Re Application Of: Takashi Ohsumi

Application No.
10/689,936Filing Date
October 22, 2003Examiner
F. Toledo

Customer No.

Group Art Unit
2823Confirmation No.
4027Invention: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING
MEMBER WITH REDUCED THERMAL STRESSCOMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

Check applicable statement herebelow:


Statement Under 37 CFR 1.97(e)(1)

- ☐ Each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

Statement Under 37 CFR 1.97(e)(2)

- ☒ No item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.

Dated: April 25, 2005


Signature
ANDREW J. TELESZ, JR.
REG. NO. 33,581

VOLENTINE FRANCOS & WHITT, P.L.L.C.
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Substitute for form 1449-PTO

Substitute for form 1449/FTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)

Sheet 1 of 1

Complete if Known

Application Number	10/689,936
Filing Date	October 22, 2003
First Named Inventor	Takashi Ohsumi
Art Unit	2823
Examiner Name	F. Toledo
Attorney Docket Number	11Z-003D2C

[illegible][illegible]

Examiner
Signature

Date Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST 3). ⁴ For the appropriate symbols as indicated on the document under WIPO Standard ST 16 if possible. ⁵ Applicant is to place a check mark here if English language translation is attached.

This collection of information is required by 37 CFR 1.97 and 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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ATTY DOCKET #: IIZ.003D26

APPLICANT: Takashi Ohsumi APR 25 2005 DUE DATE:

SERIAL NO.: 10/689,936

FILING DATE: October 22, 2003

TITLE: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL
STRESS

RECEIPT OF THE FOLLOWING PAPERS IS ACKNOWLEDGED:

Transmittal of Information Disclosure Statement; Statement Under 37 C.F.R.
1.97(e) Accompanying Information Disclosure Statement; PTO/SB/08A Form;
and Letter of Related Application.

DATE: April 25, 2005

ATTY: AJT

[Check No. N/A]